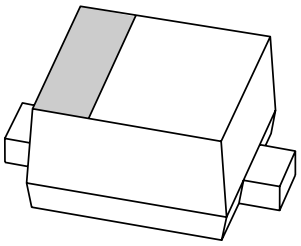
DATA SHEET



1PS79SB30
Schottky barrier diode

Product data sheet

2001 Feb 20

NXP founded by Philips

Schottky barrier diode 1PS79SB30

FEATURES

- Very low forward voltage
- Very low reverse current
- Guard ring protected
- Ultra small SMD package.

APPLICATIONS

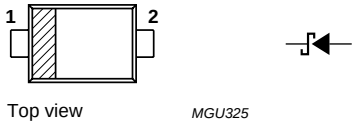
- Ultra high-speed switching
- Voltage clamping
- Protection circuits
- Blocking diodes
- Low power consumption applications (e.g. hand-held applications).

DESCRIPTION

Planar Schottky barrier diode encapsulated in a SC-79 (SOD523) ultra small SMD plastic package.

PINNING

PIN	DESCRIPTION
1	cathode
2	anode



Marking code: G1.

Fig.1 Simplified outline (SC-79; SOD523) and symbol.

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_R	continuous reverse voltage		–	40	V
I_F	continuous forward current		–	200	mA
I_{FRM}	repetitive peak forward current	$t_p \leq 1$ s; $\delta \leq 0.5$	–	300	mA
I_{FSM}	non-repetitive peak forward current	t = 8.3 ms half sinewave; JEDEC method	–	1	A
T_{stg}	storage temperature		−65	+150	°C
T_j	junction temperature		–	150	°C
T_{amb}	operating ambient temperature		−65	+150	°C

ELECTRICAL CHARACTERISTICS

T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V_F	forward voltage	see Fig.2			
		I_F = 0.1 mA	190	220	mV
		I_F = 1 mA	250	290	mV
		I_F = 10 mA	320	360	mV
		I_F = 100 mA	440	500	mV
		I_F = 200 mA	520	600	mV
I_R	continuous reverse current	V_R = 25 V; note 1; see Fig.3	–	0.5	μA
C_d	diode capacitance	V_R = 1 V; f = 1 MHz; see Fig.4	–	20	pF

Note

1. Pulse test: pulse width = 300 μs; δ = 0.02.

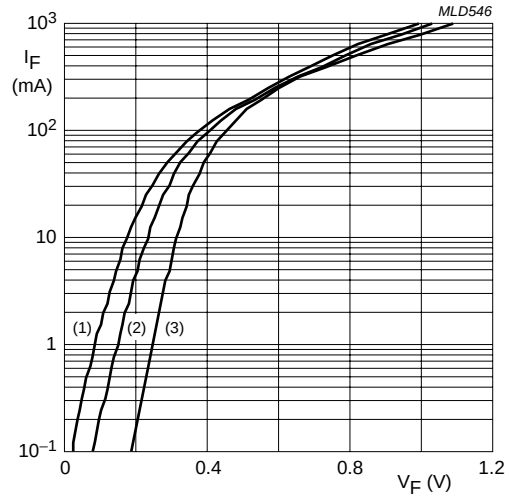
THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j\text{-}a}$	thermal resistance from junction to ambient	note 1	450	K/W

Note

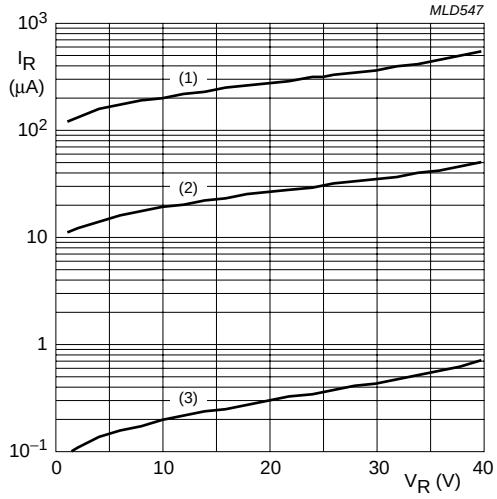
1. Refer to SC-79 (SOD523) standard mounting conditions.

GRAPHICAL DATA



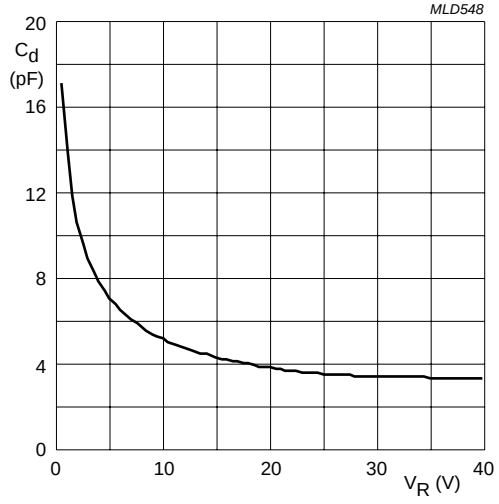
(1) T_{amb} = 125 °C.
(2) T_{amb} = 85 °C.
(3) T_{amb} = 25 °C.

Fig.2 Forward current as a function of forward voltage; typical values.



(1) T_{amb} = 125 °C.
(2) T_{amb} = 85 °C.
(3) T_{amb} = 25 °C.

Fig.3 Reverse current as a function of reverse voltage; typical values.

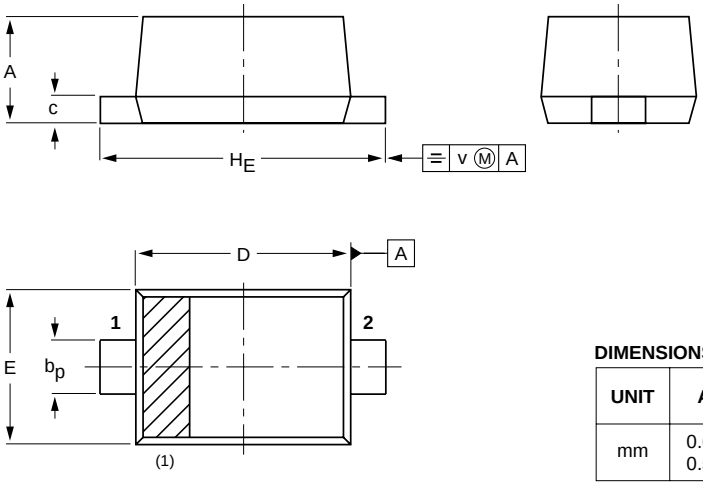


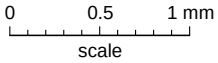
f = 1 MHz; T_{amb} = 25 °C.

Fig.4 Diode capacitance as a function of reverse voltage; typical values.

PACKAGE OUTLINE

Plastic surface mounted package; 2 leads **SOD523**





DIMENSIONS (mm are the original dimensions)

UNIT	A	b_p	c	D	E	H_E	v
mm	0.65 0.58	0.34 0.26	0.17 0.11	1.25 1.15	0.85 0.75	1.65 1.55	0.1

Note

1. The marking bar indicates the cathode.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOD523			SC-79			~~98-11-25~~ 02-12-13

DATA SHEET STATUS

DOCUMENT STATUS[1]	PRODUCT STATUS[2]	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

1. Please consult the most recently issued document before initiating or completing a design.
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NXP Semiconductors

Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

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